

UMB1F THRU UMB10F MBF

1.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER Reverse Voltage - 100 to 1000 V Forward Current – 1.0A

FEATURES

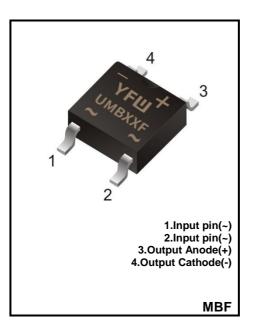
- ♦Fast reverse recovery time
- **♦** Designed for Surface Mount Application
- ◆Glass Passivated Chip Junction
- **♦Low power loss, high efficiency**
- ♦Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

♦Case: MBF

♦Terminals: Solderable per MIL-STD-750, Method 2026

Approx. Weight: 75mg / 0.0026oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	UMB1F	UMB2F	UMB4F	UMB6F	UMB8F	UMB10F	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	v
Maximum RMS voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	v
Average Rectified Output Current at T _c = 125 °C	I _o	1.0					Α	
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	I _{FSM}	35					Α	
Forward Voltage per element at 1.0A	VF	1.0		1.3		1.5		V
Maximum DC Reverse Current @T _A =25°C at Rated DC Blocking Voltage @T _A =125°C	I _R	5.0 100					μА	
Typical Junction Capacitance (Note1)	C _j	18			pF			
Maximum Reverse Recovery Time (Note2)	T _{RR}	50 75			nS			
Typical Thermal Resistance (Note3)	Rеја Rејс	80 25				°C/W		
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ + 150				°C		

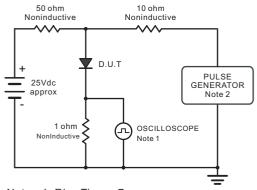
⁽¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

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⁽²⁾ Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

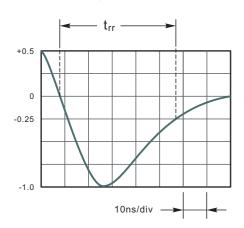


Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max. Input Impedance = 1megohm,22pF.

2. Ries Time =10ns, max. Source Impedance = 50 ohms.



Set time Base for 10ns/div

Fig.2 Maximum Average Forward Current Rating

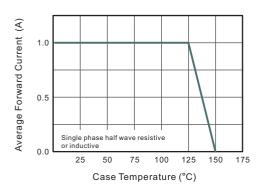


Fig.3 Typical Reverse Characteristics

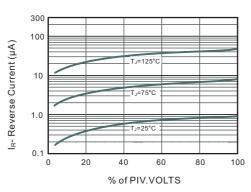


Fig.3 Typical Instaneous Forward Characteristics

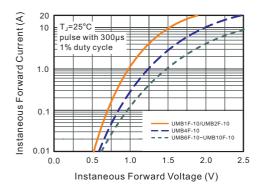
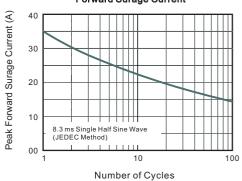


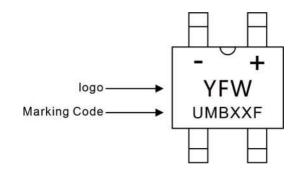
Fig.4 Maximum Non-Repetitive Peak Forward Surage Current



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Marking Diagram

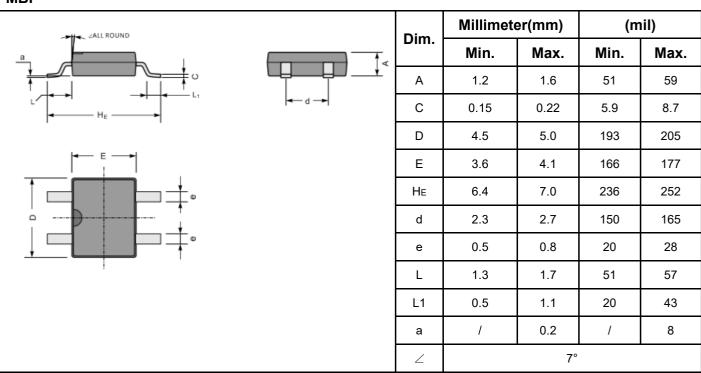


Ordering information

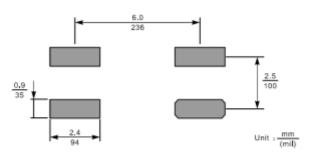
Package	Packing Description	Packing Quantity			
MBF	Tape/Reel,13"reel	5000PCS/Reel 50000PCS/Carton			

Package Dimensions

MBF



The recommended mounting pad size



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